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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	$4V \sim 6V$
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c74a-10-p

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72 ⁽¹⁾					
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20					
	EPROM Program Memory (x14 words)	512	1K	1K	2К	2К	—					
lemory	ROM Program Memory (14K words)	_	_	_	_	_	2К					
	Data Memory (bytes)	36	36	68	128	128	128					
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2					
eripherals	Capture/Compare/ PWM Module(s)	—	_	—	—	1	1					
	Serial Port(s) (SPI/I ² C, USART)	_	_	—	—	SPI/I ² C	SPI/I ² C					
	Parallel Slave Port	_	—	—	_	_	—					
	A/D Converter (8-bit) Channels	4	4	4	4	5	5					
	Interrupt Sources	4	4	4	4	8	8					
	I/O Pins	13	13	13	13	22	22					
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5					
atures	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes					
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes					
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP					

TABLE 1-1: PIC16C7XX FAMILY OF DEVCES

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Oper- ation (MHz)	20	20	20	20
Memory	EPROM Program Memory (x14 words)	4K	4K	8K	8K
	Data Memory (bytes)	192	192	368	368
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Mod- ule(s)	2	2	2	2
	Serial Port(s) (SPI/I ² C, US- ART)	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART	SPI/I ² C, USART
	Parallel Slave Port	—	Yes	—	Yes
	A/D Converter (8-bit) Channels	5	8	5	8
	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
eatures	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

NOTES:

4.2.2.1 STATUS REGISTER Applicable Devices 72|73|73A|74|74A|76|77

The STATUS register, shown in Figure 4-7, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

- **Note 1:** For those devices that do not use bits IRP and RP1 (STATUS<7:6>), maintain these bits clear to ensure upward compatibility with future products.
- Note 2: The C and DC bits operate as a borrow and digit borrow bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x	
IRP	RP1	RP0	TO	PD	Z	DC	С	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 7:	1 = Bank 2	ster Bank \$ 2, 3 (100h 0, 1 (00h -	- 1FFh)	used for ir	ndirect addr	essing)		
bit 6-5:	11 = Bank 10 = Bank 01 = Bank 00 = Bank	: Register E < 3 (180h - < 2 (100h - < 1 (80h - F < 0 (00h - 7 k is 128 by	1FFh) 17Fh) Fh) ′Fh)	ct bits (use	ed for direct	addressin	g)	
oit 4:	•			struction,	or sleep ir	struction		
bit 3:	•	r-down bit oower-up o ecution of t	•					
bit 2:		sult of an a			peration is z			
bit 1:	1 = A carr	y-out from	the 4th lo	w order bi	N, SUBLW, S t of the resu bit of the res	It occurred		r borrow the polarity is reversed
bit 0:	1 = A carr 0 = No car Note: For	y-out from rry-out fror borrow the berand. For	the most n the mos polarity is	significant t significar s reversed		esult occuri result occu ion is exec	red irred uted by add	ding the two's complement of the either the high or low order bit o

FIGURE 4-7: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

5.3 <u>PORTC and TRISC Registers</u> Applicable Devices

72 73 73A 74 74A 76 77

PORTC is an 8-bit bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC

BCF	STATUS,	RP0	;	Select Bank 0
BCF	STATUS,	RP1	;	PIC16C76/77 only
CLRF	PORTC		;	Initialize PORTC by
			;	clearing output
			;	data latches
BSF	STATUS,	RP0	;	Select Bank 1
MOVLW	0xCF		;	Value used to
			;	initialize data
			;	direction
MOVWF	TRISC		;	Set RC<3:0> as inputs
			;	RC<5:4> as outputs
			;	RC<7:6> as inputs

FIGURE 5-6: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)

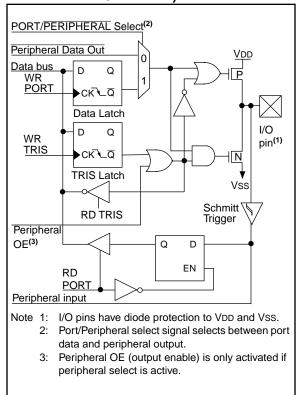


TABLE 5-5:PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input
RC1/T1OSI/CCP2 ⁽¹⁾	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/ Compare2 output/PWM2 output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and 2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (PC mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output
RC6/TX/CK ⁽²⁾	bit6	ST	Input/output port pin or USART Asynchronous Transmit, or USART Synchronous Clock
RC7/RX/DT ⁽²⁾	bit7	ST	Input/output port pin or USART Asynchronous Receive, or USART Synchronous Data

Legend: ST = Schmitt Trigger input

Note 1: The CCP2 multiplexed function is not enabled on the PIC16C72.

2: The TX/CK and RX/DT multiplexed functions are not enabled on the PIC16C72.

11.3 SPI Mode for PIC16C76/77

Γ

This section contains register definitions and operational characteristics of the SPI module on the PIC16C76 and PIC16C77 only.

FIGURE 11-7: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)(PIC16C76/77)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0	
SMP	CKE	D/Ā	Р	S	R/W	UA	BF	R = Readable bit
bit7							bit0	W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset
bit 7:	<u>SPI Ma</u> 1 = Inpu 0 = Inpu <u>SPI Sla</u>	<u>ster Mod</u> ut data sa ut data sa ut data sa <u>ve Mode</u>	ampled at o ampled at i	end of data middle of d	output time ata output tir ed in slave n			
bit 6:	$\frac{CKP = 0}{1 = Data}$ $0 = Data$ $\frac{CKP = 1}{1 = Data}$	<u>0</u> a transmi a transmi <u>1</u> a transmi	itted on ris itted on fal itted on fal	ect (Figure ing edge of ling edge o ling edge o ing edge of	f SCK f SCK	e 11-12, and	d Figure 11-	13)
bit 5:	1 = Indi	cates tha	t the last b) ed or transmi ed or transmi			
bit 4:	detecte 1 = Indi	d last, SS cates tha	SPEN is cl	eared) t has been	cleared whe			lisabled, or when the Start bit is
bit 3:	detecte 1 = Indi	d last, SS cates tha	SPEN is cl	eared) t has been	cleared whe			lisabled, or when the Stop bit is
bit 2:	This bit	holds th match to d	ne R/W bit				dress match	. This bit is only valid from the
bit 1:	1 = Indi	cates tha	t the user	it I ² C mode needs to u I to be upda	pdate the ad	dress in the	e SSPADD re	egister
bit 0:	BF: Buf	fer Full S	tatus bit					
	1 = Rec 0 = Rec	eive com eive not	complete,	es) PBUF is ful SSPBUF is				
	1 = Trar		rogress, S	SPBUF is t PBUF is en				

TABLE 12-3: BAUD RATES FOR SYNCHRONOUS MODE

BAUD	Fosc = 2	20 MHz	SPBRG	16 MHz		SPBRG	10 MHz		SPBRG	7.15909 I	MHz	SPBRG
RATE (K)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)	KBAUD	% ERROR	value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	NA	-	-	NA	-	-	NA	-	-	NA	-	-
2.4	NA	-	-	NA	-	-	NA	-	-	NA	-	-
9.6	NA	-	-	NA	-	-	9.766	+1.73	255	9.622	+0.23	185
19.2	19.53	+1.73	255	19.23	+0.16	207	19.23	+0.16	129	19.24	+0.23	92
76.8	76.92	+0.16	64	76.92	+0.16	51	75.76	-1.36	32	77.82	+1.32	22
96	96.15	+0.16	51	95.24	-0.79	41	96.15	+0.16	25	94.20	-1.88	18
300	294.1	-1.96	16	307.69	+2.56	12	312.5	+4.17	7	298.3	-0.57	5
500	500	0	9	500	0	7	500	0	4	NA	-	-
HIGH	5000	-	0	4000	-	0	2500	-	0	1789.8	-	0
LOW	19.53	-	255	15.625	-	255	9.766	-	255	6.991	-	255

	Fosc =	5.0688 M	Hz	4 MHz			3.579545	5 MHz		1 MHz			32.768 k	Hz	
BAUD RATE (K)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-	0.303	+1.14	26
1.2	NA	-	-	NA	-	-	NA	-	-	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	-	-	NA	-	-	NA	-	-	2.404	+0.16	103	NA	-	-
9.6	9.6	0	131	9.615	+0.16	103	9.622	+0.23	92	9.615	+0.16	25	NA	-	-
19.2	19.2	0	65	19.231	+0.16	51	19.04	-0.83	46	19.24	+0.16	12	NA	-	-
76.8	79.2	+3.13	15	76.923	+0.16	12	74.57	-2.90	11	83.34	+8.51	2	NA	-	-
96	97.48	+1.54	12	1000	+4.17	9	99.43	+3.57	8	NA	-	-	NA	-	-
300	316.8	+5.60	3	NA	-	-	298.3	-0.57	2	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	1267	-	0	100	-	0	894.9	-	0	250	-	0	8.192	-	0
LOW	4.950	-	255	3.906	-	255	3.496	-	255	0.9766	-	255	0.032	-	255

TABLE 12-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD	Fosc = 2	20 MHz	SPBRG	16 MHz		SPBRG	10 MHz		SPBRG	7.15909	MHz	SPBRG
RATE		% ERROR	value		%	value		%	value		% ERROR	value
(K)	KBAUD	ERROR	(decimal)	RBAUD	ERROR	(decimal)	REAUD	ERROR	(decimal)	REAUD	EKKUK	(decimal)
0.3	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1.2	1.221	+1.73	255	1.202	+0.16	207	1.202	+0.16	129	1.203	+0.23	92
2.4	2.404	+0.16	129	2.404	+0.16	103	2.404	+0.16	64	2.380	-0.83	46
9.6	9.469	-1.36	32	9.615	+0.16	25	9.766	+1.73	15	9.322	-2.90	11
19.2	19.53	+1.73	15	19.23	+0.16	12	19.53	+1.73	7	18.64	-2.90	5
76.8	78.13	+1.73	3	83.33	+8.51	2	78.13	+1.73	1	NA	-	-
96	104.2	+8.51	2	NA	-	-	NA	-	-	NA	-	-
300	312.5	+4.17	0	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	312.5	-	0	250	-	0	156.3	-	0	111.9	-	0
LOW	1.221	-	255	0.977	-	255	0.6104	-	255	0.437	-	255

	Fosc =	5.0688 MI	Hz	4 MHz			3.57954	5 MHz		1 MHz			32.768 k	Hz	
BAUD RATE (K)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
0.3	0.31	+3.13	255	0.3005	-0.17	207	0.301	+0.23	185	0.300	+0.16	51	0.256	-14.67	1
1.2	1.2	0	65	1.202	+1.67	51	1.190	-0.83	46	1.202	+0.16	12	NA	-	-
2.4	2.4	0	32	2.404	+1.67	25	2.432	+1.32	22	2.232	-6.99	6	NA	-	-
9.6	9.9	+3.13	7	NA	-	-	9.322	-2.90	5	NA	-	-	NA	-	-
19.2	19.8	+3.13	3	NA	-	-	18.64	-2.90	2	NA	-	-	NA	-	-
76.8	79.2	+3.13	0	NA	-	-	NA	-	-	NA	-	-	NA	-	-
96	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
300	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
500	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
HIGH	79.2	-	0	62.500	-	0	55.93	-	0	15.63	-	0	0.512	-	0
LOW	0.3094	-	255	3.906	-	255	0.2185	-	255	0.0610	-	255	0.0020	-	255

Applicable Devices 72 73 73A 74 74A 76 77

17.5 <u>Timing Diagrams and Specifications</u>

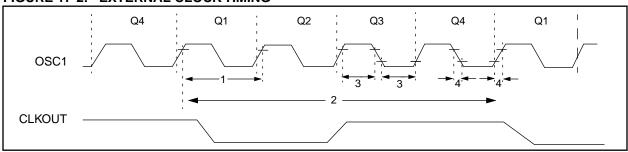


FIGURE 17-2: EXTERNAL CLOCK TIMING

TABLE 17-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	—	—	ns	XT and RC osc mode
		(Note 1)	250	—	—	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	_	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	—	DC	ns	TCY = 4/FOSC
3	TosL,	External Clock in (OSC1) High or	100	_	—	ns	XT oscillator
	TosH	Low Time	2.5	_	_	μs	LP oscillator
			15	_	_	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise or	_	_	25	ns	XT oscillator
	TosF	Fall Time	_	_	50	ns	LP oscillator
				_	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices 72 73 73A 74 74A 76 77

19.2 DC Characteristics: PIC16LC73A/74A-04 (Commercial, Industrial)

DC CHA	RACTERISTICS			ard Ope ing tem			itions (unless otherwise stated) $0^{\circ}C$ $\leq TA \leq +85^{\circ}C$ for industrial and C $\leq TA \leq +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2,5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μΑ	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μΑ	BOR enabled VDD = 5.0V
D020 D021 D021A	Power-down Current (Note 3,5)	IPD	- - -	7.5 0.9 0.9	30 5 5	μΑ μΑ μΑ	$VDD = 3.0V, WDT enabled, -40^{\circ}C to +85^{\circ}C$ $VDD = 3.0V, WDT disabled, 0^{\circ}C to +70^{\circ}C$ $VDD = 3.0V, WDT disabled, -40^{\circ}C to +85^{\circ}C$
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD \overline{MCLR} = VDD; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 19-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

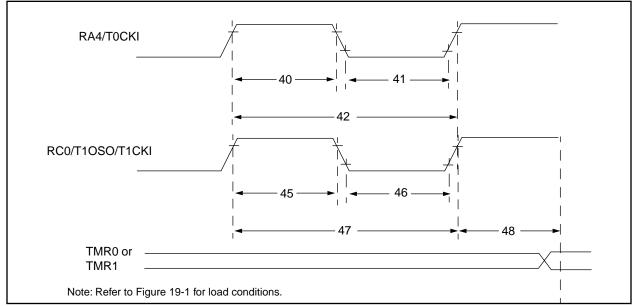


TABLE 19-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse V	Vidth	No Prescaler	0.5Tcy + 20	—	—	ns	Must also meet
				With Prescaler	10	_	_	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse W	/idth	No Prescaler	0.5TCY + 20	-	—	ns	Must also meet
				With Prescaler	10	—	—	ns	parameter 42
42*	Tt0P			No Prescaler	Tcy + 40	_	—	ns	
				With Prescaler	Greater of: 20 or <u>Tcy + 40</u> N	-	_	ns	N = prescale value (2, 4,, 256)
45*	45* Tt1H T1CKI High Time Synchrono		Synchronous, P	Prescaler = 1	0.5Tcy + 20	- 1	—	ns	Must also meet
			Synchronous,	PIC16 C 7X	15	-	—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 7X	25	-	—	ns	
			Asynchronous	PIC16 C 7X	30	—	—	ns	
				PIC16 LC 7X	50	—	—	ns	
46*	16* Tt1L T1CKI Low Time Synchronou		Synchronous, P		0.5Tcy + 20	-	—	ns	Must also meet
			Synchronous,	PIC16 C 7X	15		—	ns	parameter 47
			Prescaler = 2,4,8	PIC16 LC 7X	25	-	-	ns	
			Asynchronous	PIC16 C 7X	30	—	—	ns]
				PIC16 LC 7X	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16 C 7X	<u>Greater of:</u> 30 OR <u>TCY + 40</u> N	-	_	ns	N = prescale value (1, 2, 4, 8)
				PIC16 LC 7X	<u>Greater of:</u> 50 OR <u>TCY + 40</u> N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16 C 7X	60	-	—	ns	
				PIC16 LC 7X	100	-	—	ns	
	Ft1	Timer1 oscillator inp (oscillator enabled b			DC	-	200	kHz	
48	TCKEZtmr1	Delay from external	clock edge to tin	ner increment	2Tosc	—	7Tosc	-	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 72 73 73A 74 74A 76 77

20.2 DC Characteristics: PIC16LC76/77-04 (Commercial, Industrial)

DC CHA	RACTERISTICS			ard Ope ing tem	•		itions (unless otherwise stated) $D^{\circ}C$ $\leq TA \leq +85^{\circ}C$ for industrial and C $\leq TA \leq +70^{\circ}C$ for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	Svdd	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2,5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3,5)		-	0.9	5	μA	VDD = $3.0V$, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	∆IBOR	-	350	425	μA	BOR enabled VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD \overline{MCLR} = VDD; WDT enabled/disabled as specified.

- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSs.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices 72 73 73A 74 74A 76 77

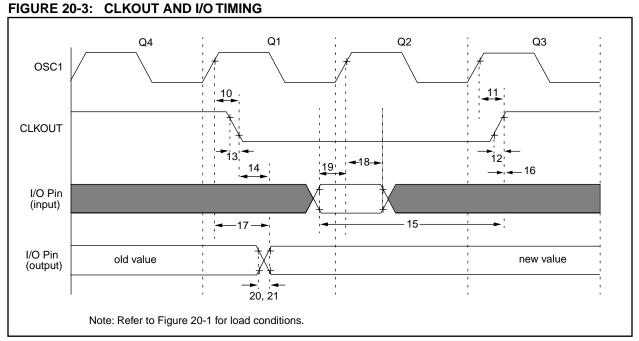


TABLE 20-3:	CLKOUT AND I/O TIMING REQUIREMENTS
IADEE 20-3.	

Param No.	Sym	Characteristic		Min	Тур†	Мах	Units	Conditions
10*	TosH2ckL	OSC1 [↑] to CLKOUT↓	_	75	200	ns	Note 1	
11*	TosH2ckH	OSC1 [↑] to CLKOUT [↑]		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		_	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		_	—	0.5Tcy + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		Tosc + 200	—	_	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT \uparrow		0	—	_	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		_	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to	PIC16 C 76/77	100	—	_	ns	
		Port input invalid (I/O in hold time)	PIC16 LC 76/77	200	-	_	ns	
19*	TioV2osH	Port input valid to OSC1↑	(I/O in setup time)	0	—	_	ns	
20*	TioR	Port output rise time	PIC16 C 76/77	_	10	40	ns	
			PIC16 LC 76/77	_	—	80	ns	
21*	TioF	Port output fall time	PIC16 C 76/77	_	10	40	ns	
			PIC16 LC 76/77	_	—	80	ns	
22††*	Tinp	INT pin high or low time		Тсү	—	—	ns	
23††*	Trbp	RB7:RB4 change INT hig	n or low time	Тсү	—	—	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

t These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

Applicable Devices 72 73 73A 74 74A 76 77



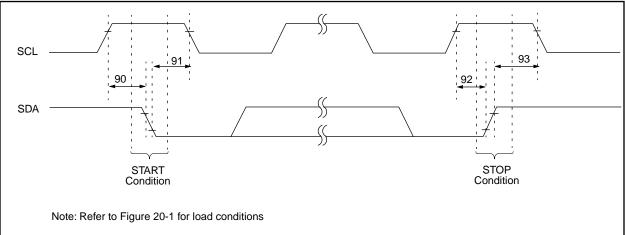
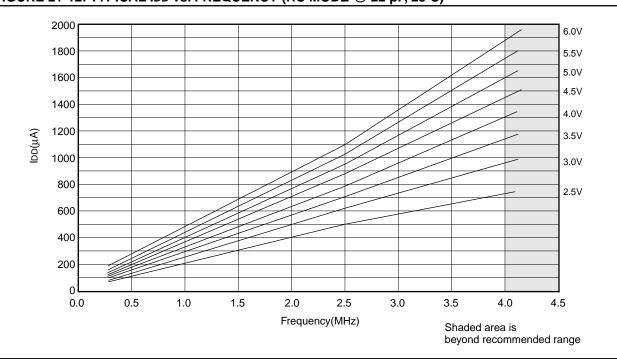


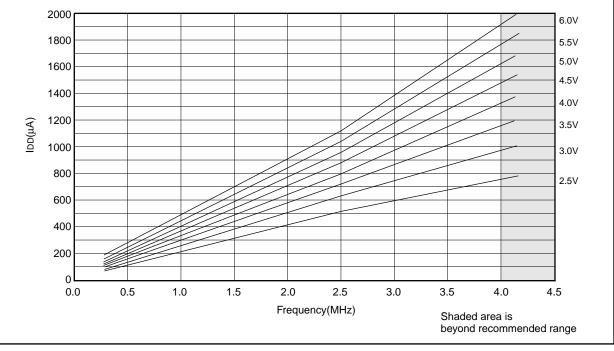
TABLE 20-9: I²C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур	Max	Units	Conditions
90	TSU:STA	START condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated START
		Setup time	400 kHz mode	600	-	—		condition
91	THD:STA	START condition	100 kHz mode	4000	—	—	ns	After this period the first clock
		Hold time	400 kHz mode	600	—	—	115	pulse is generated
92	Tsu:sto	STOP condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
93	THD:STO	STOP condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—	113	

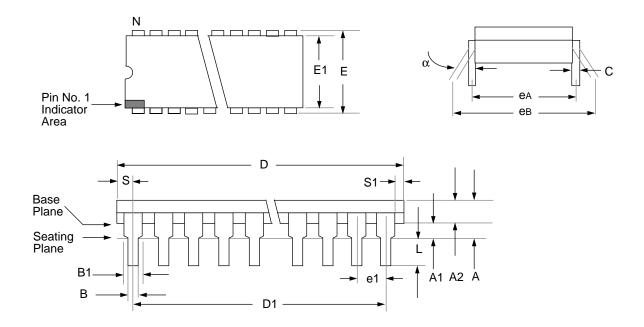
Applicable Devices 72 73 73A 74 74A 76 77 FIGURE 21-12: TYPICAL IDD vs. FREQUENCY (RC MODE @ 22 pF, 25°C)





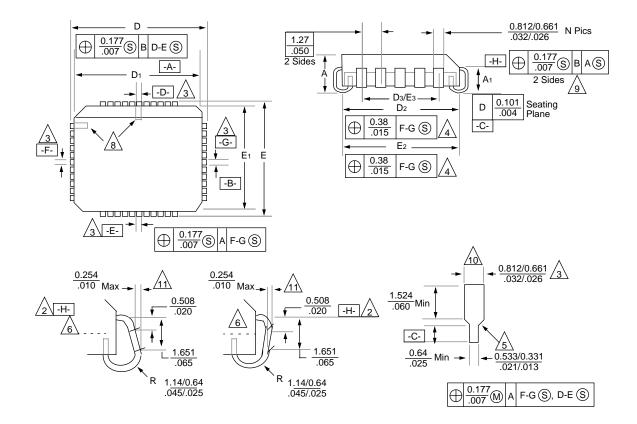


22.4 40-Lead Plastic Dual In-line (600 mil) (P)



		Package Gro	up: Plastic Dual	In-Line (PLA)		
	Millimeters					
Symbol	Min	Мах	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
А	_	5.080		_	0.200	
A1	0.381	-		0.015	-	
A2	3.175	4.064		0.125	0.160	
В	0.355	0.559		0.014	0.022	
B1	1.270	1.778	Typical	0.050	0.070	Typical
С	0.203	0.381	Typical	0.008	0.015	Typical
D	51.181	52.197		2.015	2.055	
D1	48.260	48.260	Reference	1.900	1.900	Reference
E	15.240	15.875		0.600	0.625	
E1	13.462	13.970		0.530	0.550	
e1	2.489	2.591	Typical	0.098	0.102	Typical
eA	15.240	15.240	Reference	0.600	0.600	Reference
eB	15.240	17.272		0.600	0.680	
L	2.921	3.683		0.115	0.145	
Ν	40	40		40	40	
S	1.270	_		0.050	_	
S1	0.508	_		0.020	-	

22.7 44-Lead Plastic Leaded Chip Carrier (Square)(PLCC)



	Pa	ackage Group: F	Plastic Leaded C	hip Carrier (PL	CC)	
	Millimeters				Inches	
Symbol	Min	Max	Notes	Min	Max	Notes
А	4.191	4.572		0.165	0.180	
A1	2.413	2.921		0.095	0.115	
D	17.399	17.653		0.685	0.695	
D1	16.510	16.663		0.650	0.656	
D2	15.494	16.002		0.610	0.630	
D3	12.700	12.700	Reference	0.500	0.500	Reference
E	17.399	17.653		0.685	0.695	
E1	16.510	16.663		0.650	0.656	
E2	15.494	16.002		0.610	0.630	
E3	12.700	12.700	Reference	0.500	0.500	Reference
Ν	44	44		44	44	
CP	-	0.102		_	0.004	
LT	0.203	0.381		0.008	0.015	

APPENDIX A:

The following are the list of modifications over the PIC16C5X microcontroller family:

- 1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
- 2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
- 3. Data memory paging is redefined slightly. STATUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compati-bility with PIC16C5X.
- 5. OPTION and TRIS registers are made addressable.
- 6. Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- 10. Wake up from SLEEP through interrupt is added.
- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. T0CKI pin is also a port pin (RA4) now.
- 14. FSR is made a full eight bit register.
- "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, Vss, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
- PCON status register is added with a Power-on Reset status bit (POR).
- 17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- Brown-out protection circuitry has been added. Controlled by configuration word bit BODEN. Brown-out reset ensures the device is placed in a reset condition if VDD dips below a fixed setpoint.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- 1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change reset vector to 0000h.

APPENDIX C: WHAT'S NEW

Added the following devices:

- PIC16C76
- PIC16C77

Removed the PIC16C710, PIC16C71, PIC16C711 from this datasheet.

Added PIC16C76 and PIC16C77 devices. The PIC16C76/77 devices have 368 bytes of data memory distributed in 4 banks and 8K of program memory in 4 pages. These two devices have an enhanced SPI that supports both clock phase and polarity. The USART has been enhanced.

When upgrading to the PIC16C76/77 please note that the upper 16 bytes of data memory in banks 1,2, and 3 are mapped into bank 0. This may require relocation of data memory usage in the user application code.

Added Q-cycle definitions to the Instruction Set Summary section.

APPENDIX D: WHAT'S CHANGED

Minor changes, spelling and grammatical changes.

Added the following note to the USART section. This note applies to all devices except the PIC16C76 and PIC16C77.

For the PIC16C73/73A/74/74A the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C76/77.

Divided SPI section into SPI for the PIC16C76/77 and SPI for all other devices.

APPENDIX E: PIC16/17 MICROCONTROLLERS

E.1 PIC12CXXX Family of Devices

		PIC12C508	PIC12C509	PIC12C671	PIC12C672
Clock	Maximum Frequency of Operation (MHz)	4	4	4	4
lomony	EPROM Program Memory	512 x 12	1024 x 12	1024 x 14	2048 x 14
lemory	Data Memory (bytes)	25	41	128	128
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
eripherals	A/D Converter (8-bit) Channels	—	—	4	4
	Wake-up from SLEEP on pin change	Yes	Yes	Yes	Yes
	I/O Pins	5	5	5	5
	Input Pins	1	1	1	1
eatures	Internal Pull-ups	Yes	Yes	Yes	Yes
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Number of Instructions	33	33	35	35
	Packages	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC	8-pin DIP, SOIC

All PIC12C5XX devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC12C5XX devices use serial programming with data pin GP1 and clock pin GP0.

E.2 PIC14C000 Family of Devices

		PIC14C000
Clock	Maximum Frequency of Operation (MHz)	20
	EPROM Program Memory (x14 words)	4K
Memory	Data Memory (bytes)	192
Memory	Timer Module(s)	TMR0 ADTMR
Peripherals	Serial Port(s) (SPI/I ² C, USART)	I ² C with SMBus Support
	Slope A/D Converter Channels	8 External; 6 Internal
	Interrupt Sources	11
	I/O Pins	22
	Voltage Range (Volts)	2.7-6.0
Features	In-Circuit Serial Programming	Yes
	Additional On-chip Features	Internal 4MHz Oscillator, Bandgap Reference, Temperature Sensor, Calibration Factors, Low Voltage Detector, SLEEP, HIBERNATE, Comparators with Programmable References (2)
	Packages	28-pin DIP (.300 mil), SOIC, SSOP

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- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
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